

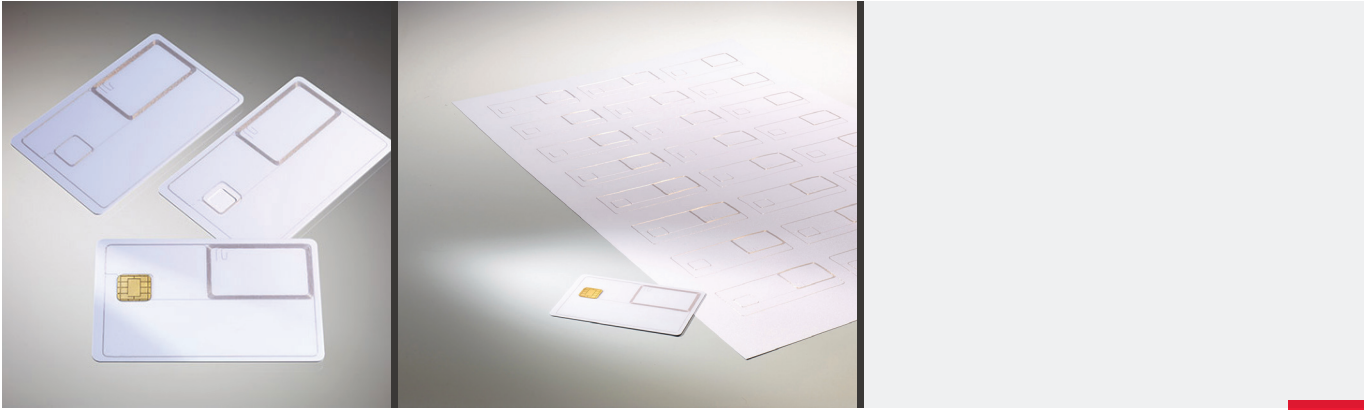


LINXENS

CONNECTING YOU TO SUCCESS

WIRE BOOSTER ANTENNA

Cost-efficiency Combined with Reliability



LINXENS's WIRE BOOSTER ANTENNA for dual-interface cards provides a reliable, robust and proven solution for the smart card market.

WIRE BOOSTER ANTENNA and the module are connected to each other by inductive coupling. The absence of any mechanical interconnection between module and antenna makes it one of the most robust dual-interface solutions available on the market today. This proven technology simplifies card production and improves yield rates.

LINXENS's WIRE BOOSTER ANTENNA leverages the advantages of wire-embedding and inductive coupling technologies. There is a choice of ID1, ID1/2 and ID2/3 antenna designs that meet EMV requirements. The antenna designs allow card embossing without any restriction.

The thin tracks of the wire antenna only occupy small area inside the card body. This provides room for creativity in case of translucent cards however also prevents "ghost images" on the card surface when applying sophisticated graphics.

The WIRE BOOSTER ANTENNA is delivered as a PRELAM® in customized sheet formats with a standard thickness of typically $200\mu\text{m} \pm 30\mu\text{m}$, and is suitable for manual as well as fully automated collation. All available PRELAM substrates are suitable for hot lamination, which enables the creation of a durable, mono-material card structure. Compared to card structures involving adhesives, such a monolithic construction significantly reduces the risk of card body delamination.

Manufacturing a card with inductive coupling technology based on LINXENS's WIRE BOOSTER ANTENNA requires no equipment investment beyond what is needed to manufacture a conventional contact-chip card. Therefore it represents one of today's most economical ways to produce dual-interface cards.

Overview

Operating Frequency

13.56 MHz

Material

PVC

Other substrates upon request

International Standards

- ISO 14443

Application Area

Dual Interface Cards for:

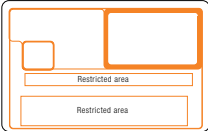
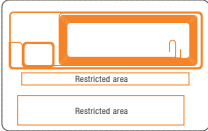

- Finance
- Transportation
- Access control
- Identification

Benefits

- Customized sheet formats available
- Full hot lamination capabilities
- Economic integration into existing card manufacturing process

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Product	Antenna Size	Dimensions	Thickness	Available IC
	ID 1	Sheet layout according to customized format	200µm ± 30µm	Infineon module S-COM8.6 with SLE78 / SLE77 chip family*
	ID 1/2	Sheet layout according to customized format	200µm ± 30µm	Infineon module S-COM8.6 with SLE78 / SLE77 chip family*
	ID 2/3	Sheet layout according to customized format	200µm ± 30µm	Infineon module S-COM8.6 with SLE78 / SLE77 chip family*

Additional memory, protocol and product configurations are available upon request.
Note: Pictures are for illustration only and are not to scale.